Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP FF 12910 Switch AC Chassis(JG619A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	6
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on part 1, and then remove part 1.
2. Unscrew the screws on part 2, and then remove part 2.
3. Push the key,and then remove part 3.
4. Unscrew the screws on part 4, and then remove part 4.
5. Unscrew the screws on part 5, and then remove part 5.
6. Unscrew the screws on part 6, and then remove part 6.
7. Unscrew the screws on part7, and then remove part 7.
8. Unscrew the screws on part 8, and then remove part 8.
9. Unscrew the screws on part 9, and then remove part 9.
10. Unscrew the screws on part 10, and then remove part 10.
11. Unscrew the screws on part 3-1, and then remove part 3-1.
12. Push the clip, and then remove part 3-2.
13. Remove part 3-1-1 from part 3-1.
14. Remove part 3-1-2 from part 3-1.
15. Unscrew the screws on part 3-2-1, and then remove part 3-2-1,3-2-2 and 3-2-3.
16. Remove 4-1 and 4-2 from part 4.
17. Unscrew the screws on part 4-3, and then remove part 4-3,4-4 from part 4.
18. Unscrew all screws left, and then remove part 4-5,4-6,4-7,4-8,4-9,4-10 from part 4.
19. Remove 5-1 from part 5.
20. Remove 5-2 from part 5.
21. Remove 7-1 from part 7.
22. Remove 7-2 from part 7.
23. Remove 8-1 from part 8.
24. Remove 8-2 from part 8.
25. Remove all the labels on part 9.
26. Unscrew the screws on part 9-1, and then remove part 9-1 form part 9.
27. Unscrew the screws on par 9-2, and then remove part 9-2 and 9-3 from part 9.
28. Unscrew the screws on PCB 9-4, and then remove PCB 9-4 from part 9.
29. Remove part 9-5 from part 9.
30. Unscrew the screws on PCB 9-6, and then remove PCB 9-6 from part 9.
31. Remove part 9-7 from part 9.
32. Unscrew the screws on part 9-8, and then remove part 9-8 from part 9.
33. Remove part 9-9 from part 9.
34. Remove part 9-10 from part 9.
35. Remove part 9-11 from part 9.
36. Remove all the labels on part 10.
37. Unscrew the screws on part 10-1, and then remove part 10-1 from part 10.
38. Unscrew the screws on PCB 10-2, and then remove PCB 10-2 from part 10.
39. Unscrew the screws on part 10-3, and then remove part 10-3 from part 10.
40. Unscrew the screws on part 10-4, and then remove part 10-4 from part 10.
41. Remove part 10-4-1 from part 10-4.
42. Remove part 10-4-2 from part 10-4.

43. Unscrew the screws on part 10-5, and then remove part 10-5 from part 10.
44. Unscrew the screws on PCB 10-6, and then remove PCB 10-6 from part 10.
45. Unscrew part 10-7, and then remove part 10-7 from part 10.
46. Unscrew the screws on another PCB 10-6, and then remove PCB 10-6 from part 10.
47. Unscrew the screws on part 10-8, and then remove part 10-8 from PCB 10-6.
48. Unscrew the screws on part 10-9, and then remove part 10-9 from part 10.
49. Unscrew the nuts on part 10-10, and then remove washers and part 10-10 from part 10.
50. Push the cilp of part 10-11, and then remove part 10-11 from part 10.
51. Remove part 10-12 from part 10.
52. Unscrew the screws on part 10-13, and then remove part 10-13 from part 10.
53. Unscrew the screws on part 10-14, and then remove part 10-14 from part 10.
54. Remove part 10-15 from part 10.
55. Remove all the labels on part 11.
56. Unscrew the screws on part 11-1, and then remove part 11-1 from part 11.
57. Unscrew the screws on PCB 11-2, and then remove PCB 11-2 from part 11.
58. Unscrew the screws on PCB 11-3, and then remove PCB 11-3 from part 11-2.
59. Remove part 10-4 from part 11.
60. Unscrew the screws on part 11-5, and then remove part 11-5 from part 11.
61. Unscrew the screws on part 11-6, and then remove part 11-6 from part 11.
62. Remove part 11-7 from part 11.
63. Unscrew the screws on part 11-8, and then remove part 11-8 from part 11.
64. Remove part 11-8-1 from part 11-8.
65. Remove part 11-8-2 from part 11-8.
66. Unscrew the screws on part 11-9, and then remove part 11-9 from part 11.
67. Unscrew the screws on part 11-10, and then remove part 11-10 from part 11.
68. Unscrew the screws on PCB 11-11, and then remove PCB 11-11 from part 11.
69. Unscrew the screws on part 11-11-1, and then remove part 11-11-1 from PCB 11-11.
70. Unscrew the screws on part 11-11-2, and then remove part 11-11-2 from PCB 11-11.
71. Unscrew the screws on part 11-12-1, and then remove part 11-12-1 from PCB 11-12.
72. Remove part 11-12-2 from part 11-12.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

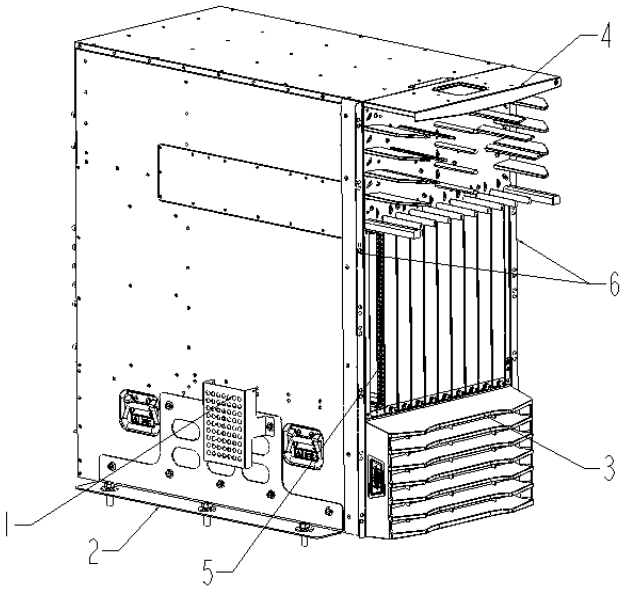

Figure 1 Front view of the product

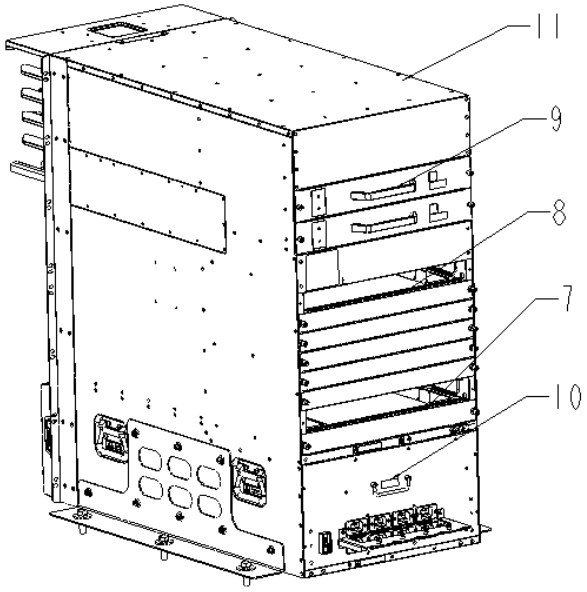

Figure 2 Rear view of the product

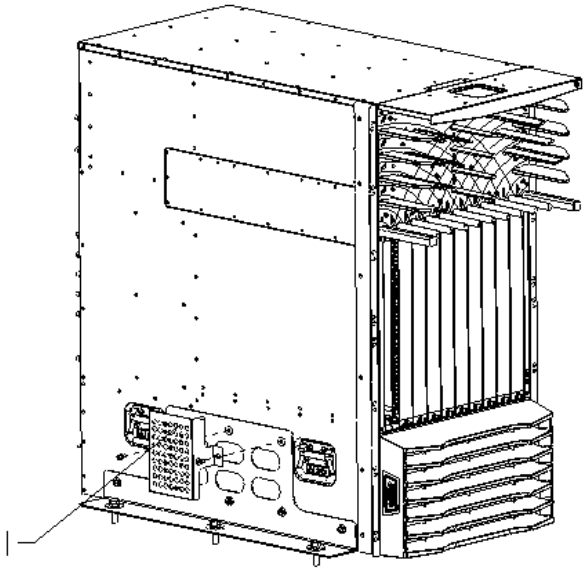

Figure 3 Treatments to the product

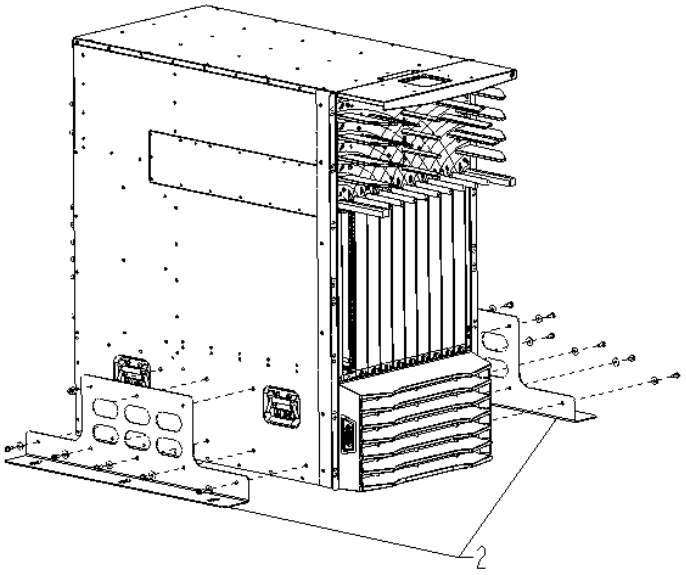

Figure 4 Treatments to the product

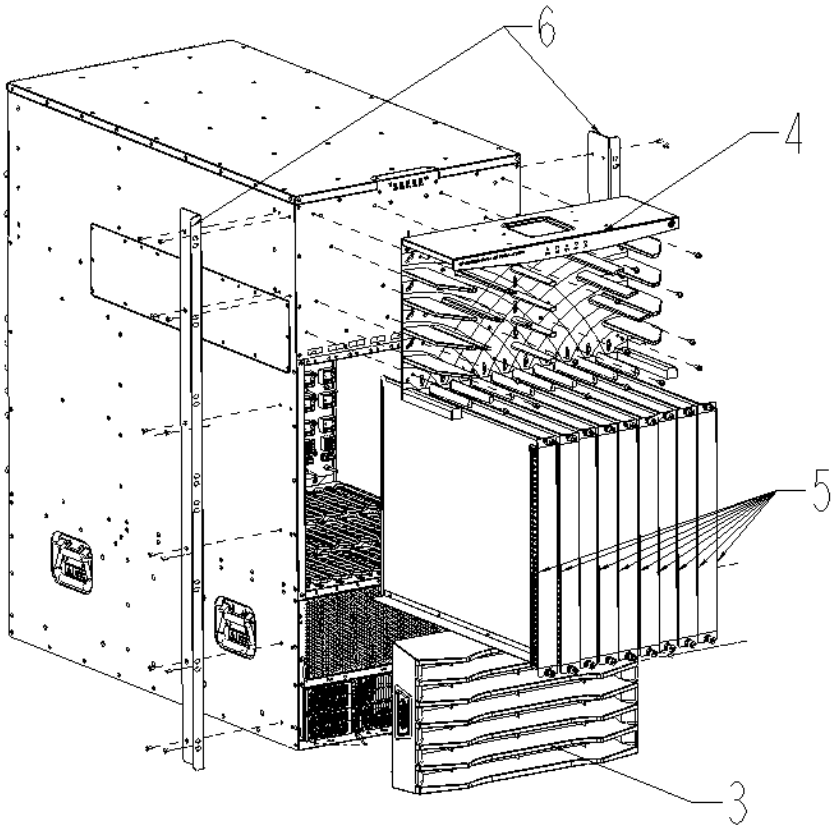

Figure 5 Treatments to the product

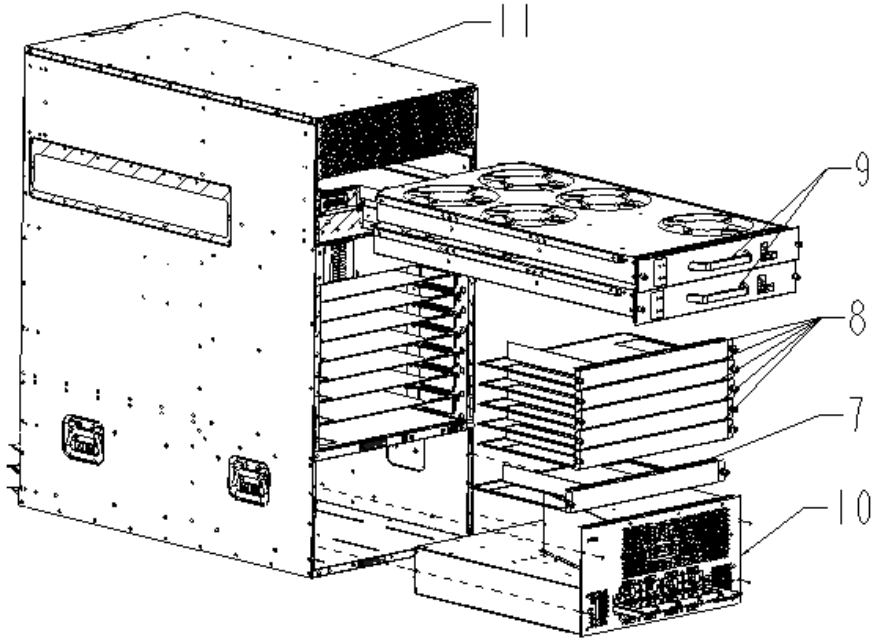

Figure 6 Treatments to the product

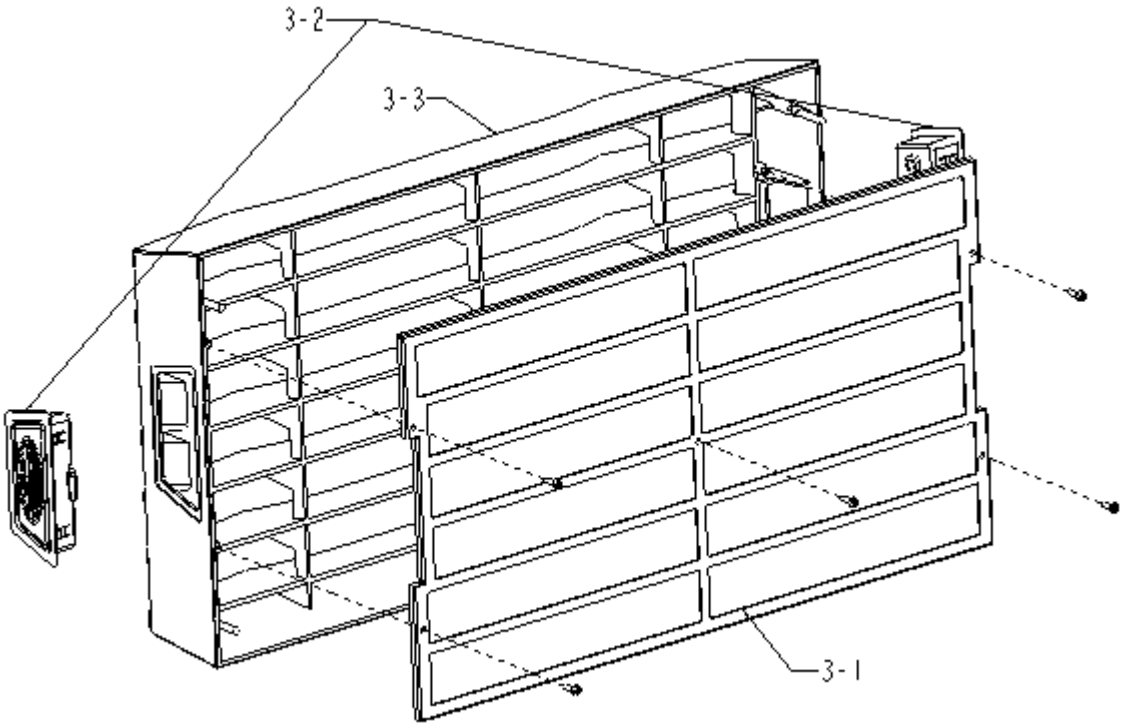

Figure 7 Treatments to the part 3

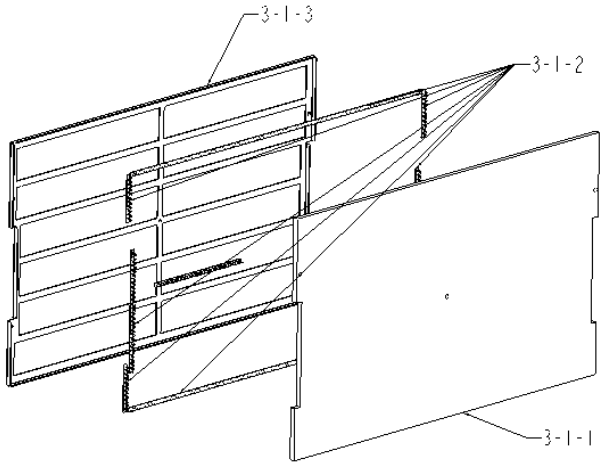

Figure 8 Treatments to the part 3-1

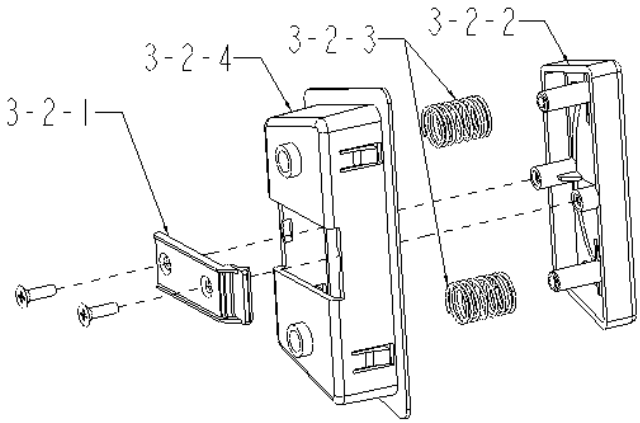

Figure 9 Treatments to the part 3-2

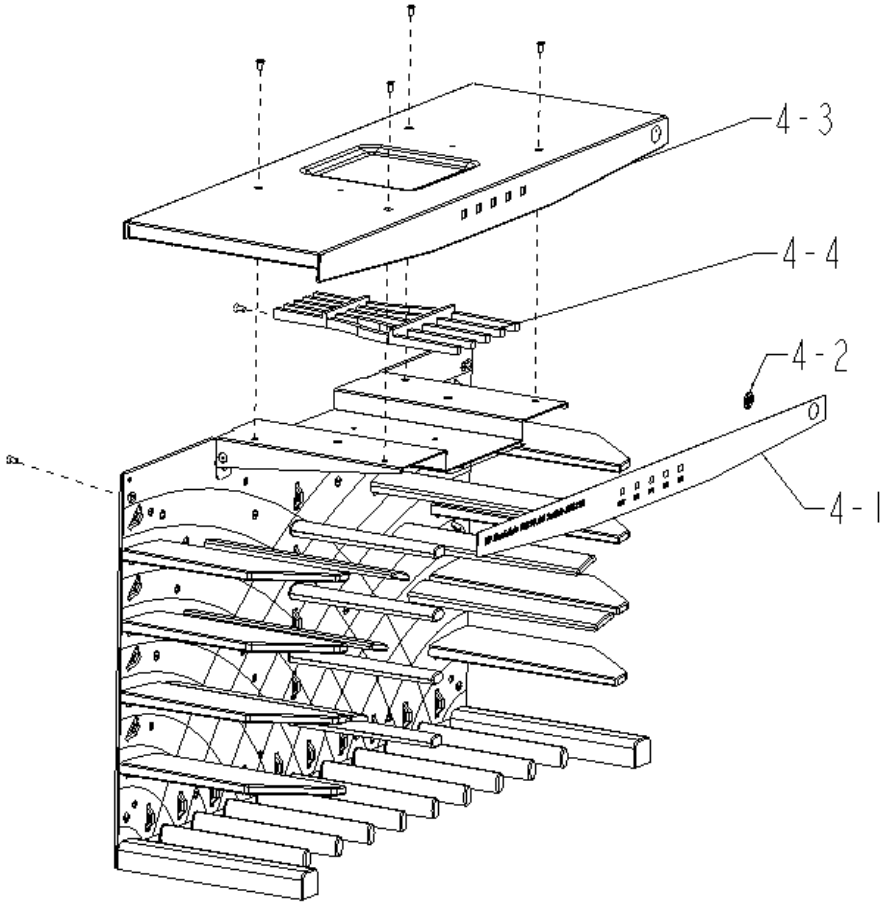

Figure 10 Treatments to the part 4

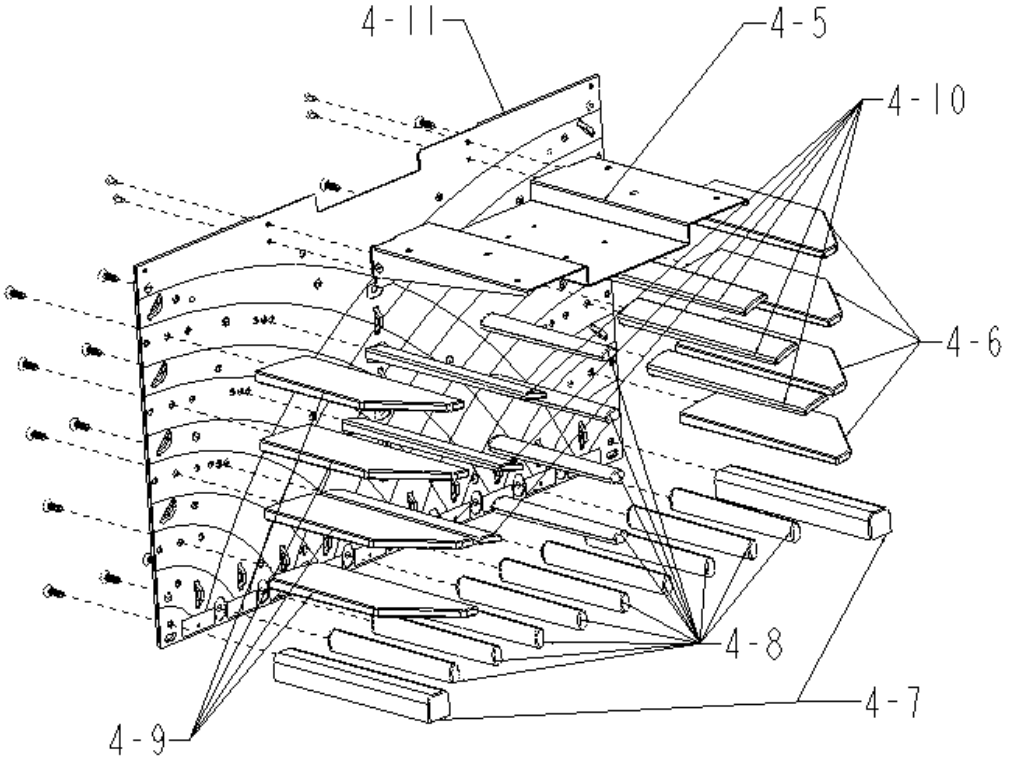

Figure 11 Treatments to the part 4

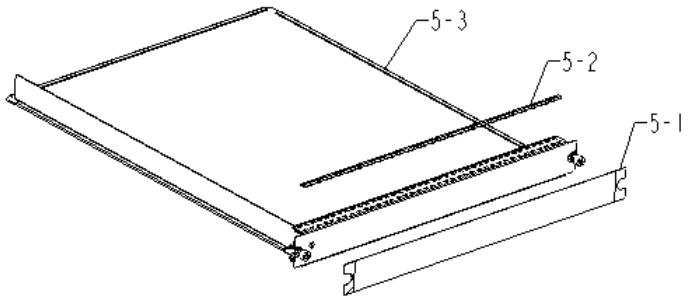

Figure 12 Treatments to the part 5

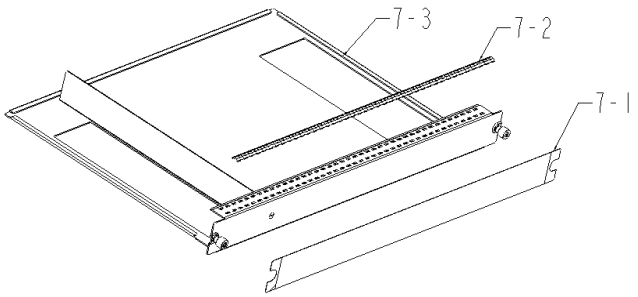

Figure 13 Treatments to the part 7

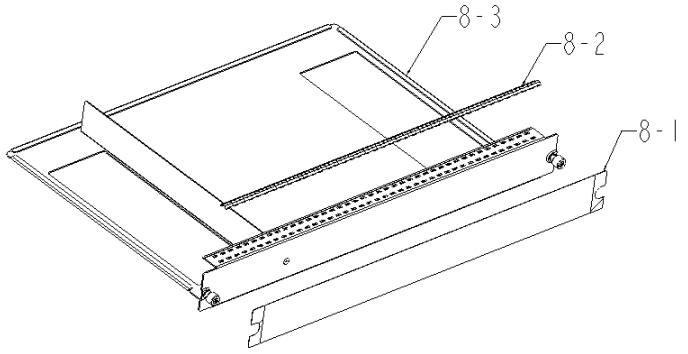

Figure 14 Treatments to the part 8

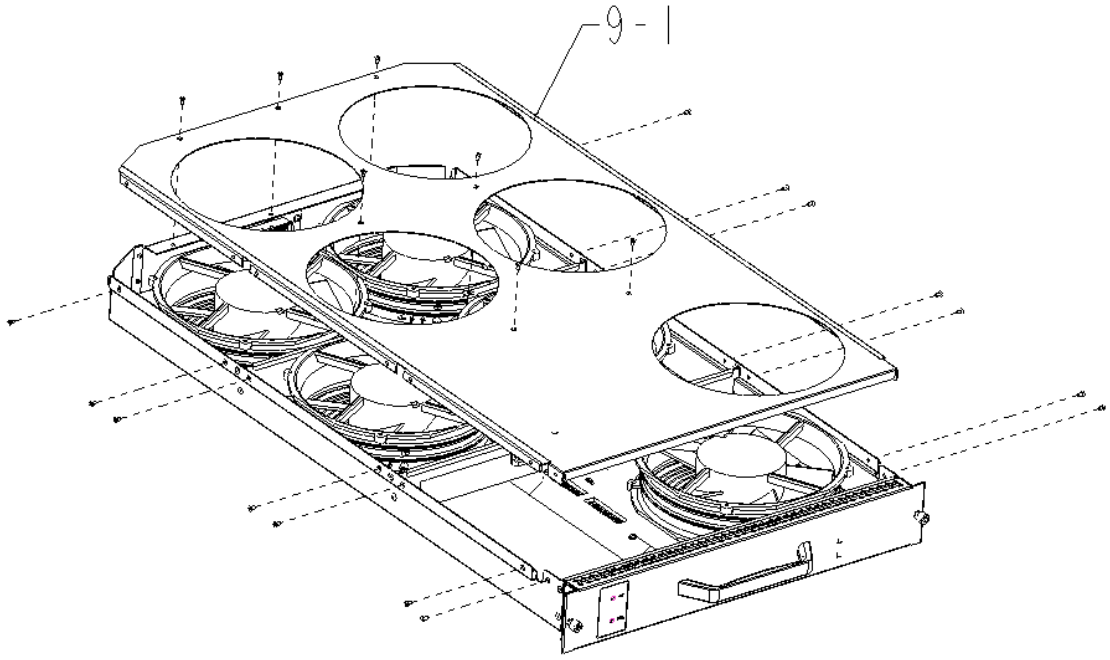

Figure 15 Treatments to the part 9

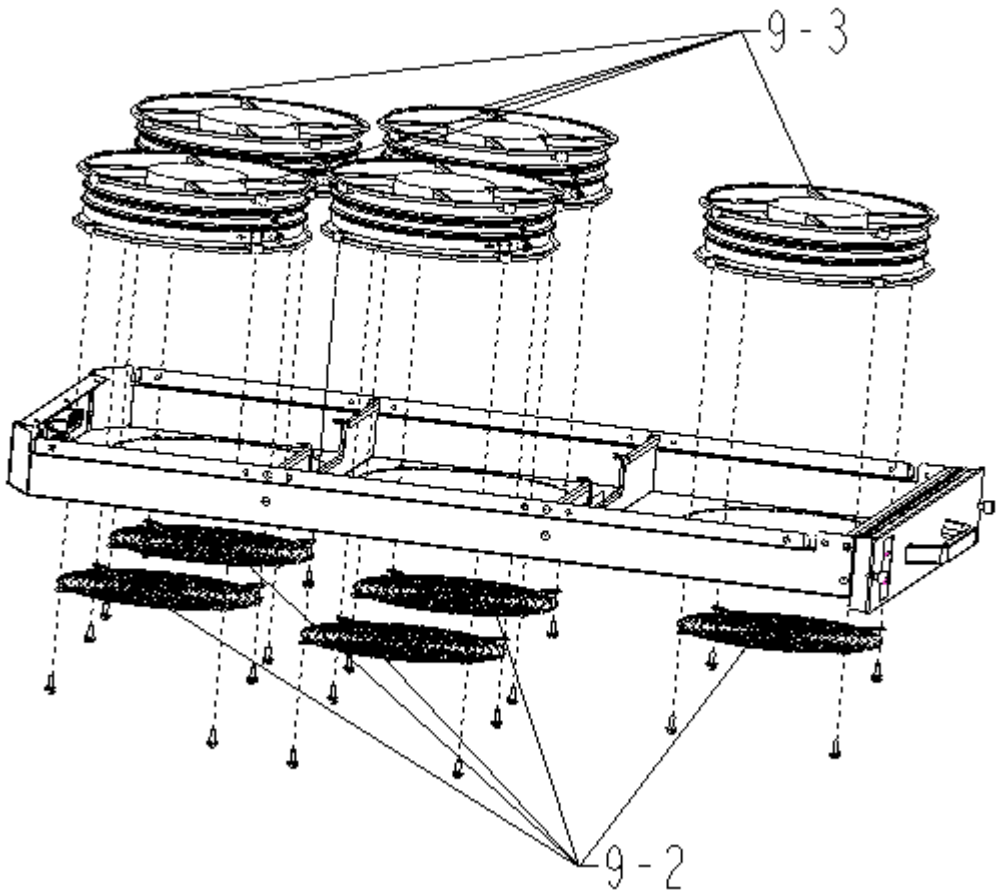

Figure 16 Treatments to the part 9

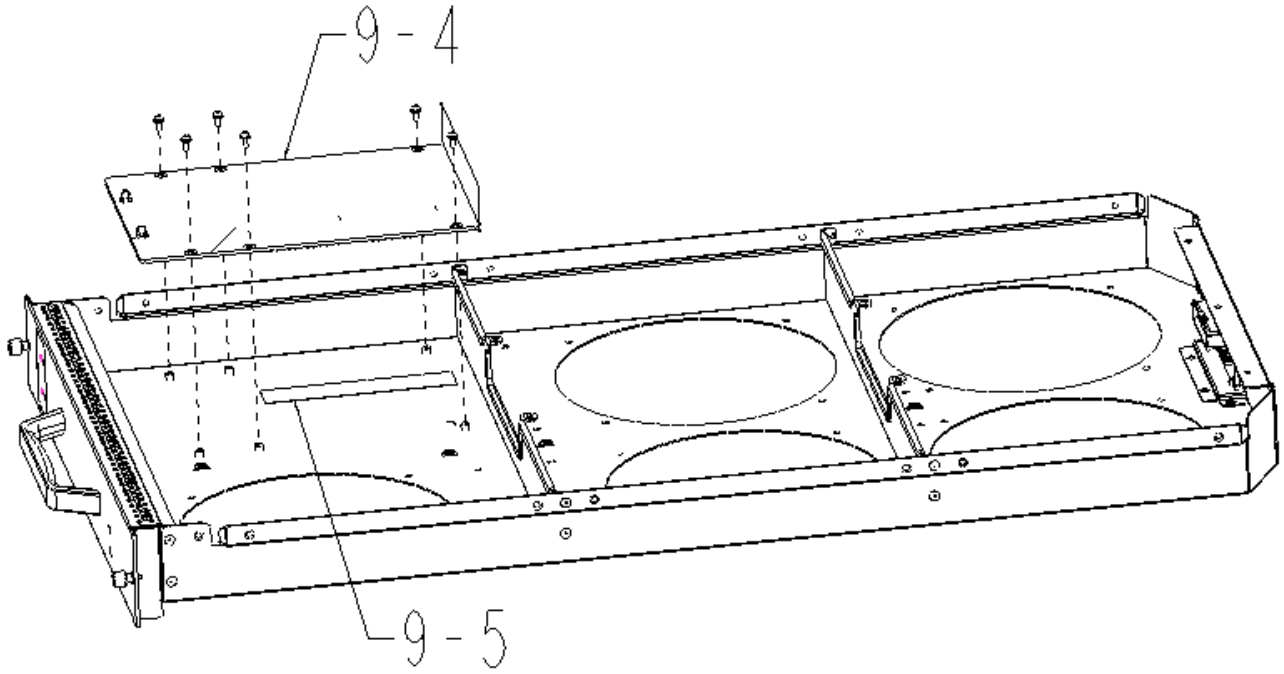

Figure 17 Treatments to the part 9

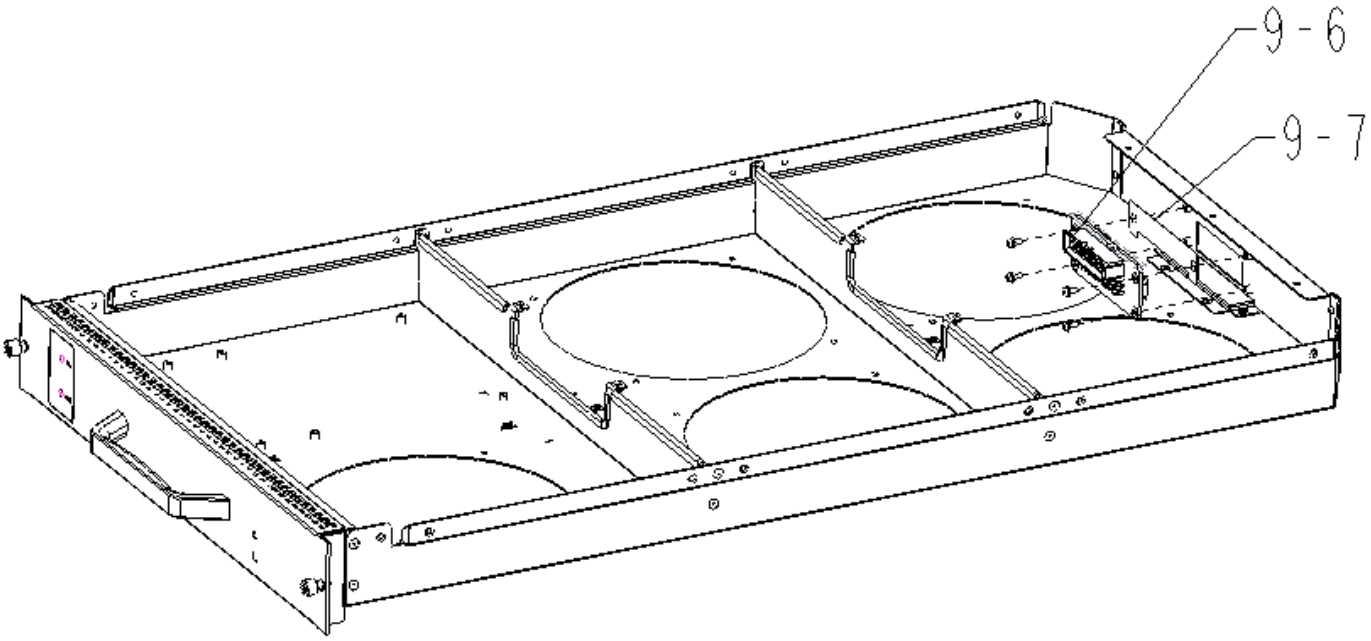

Figure 18 Treatments to the part 9

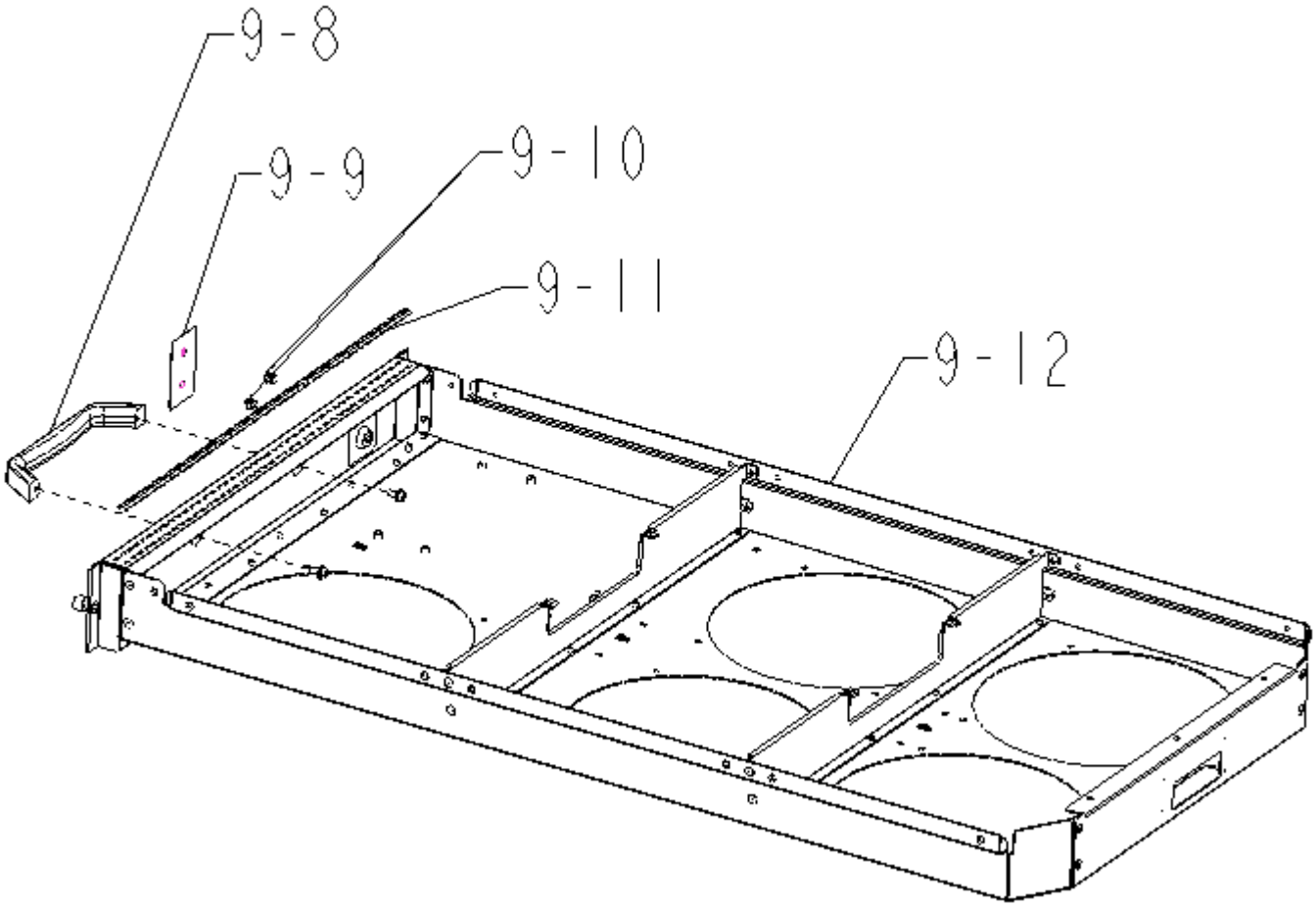

Figure 19 Treatments to the part 9

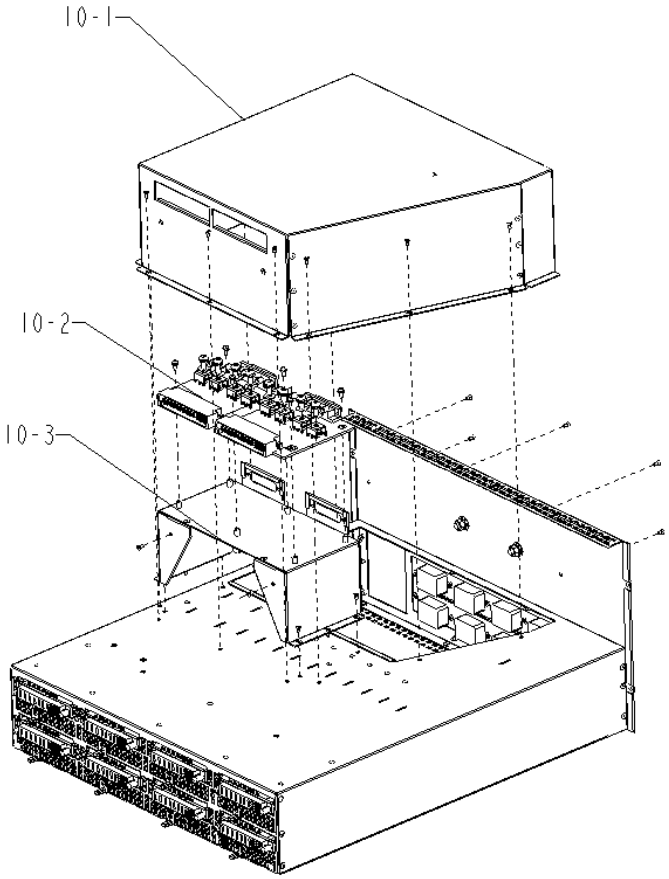

Figure 20 Treatments to the part 10

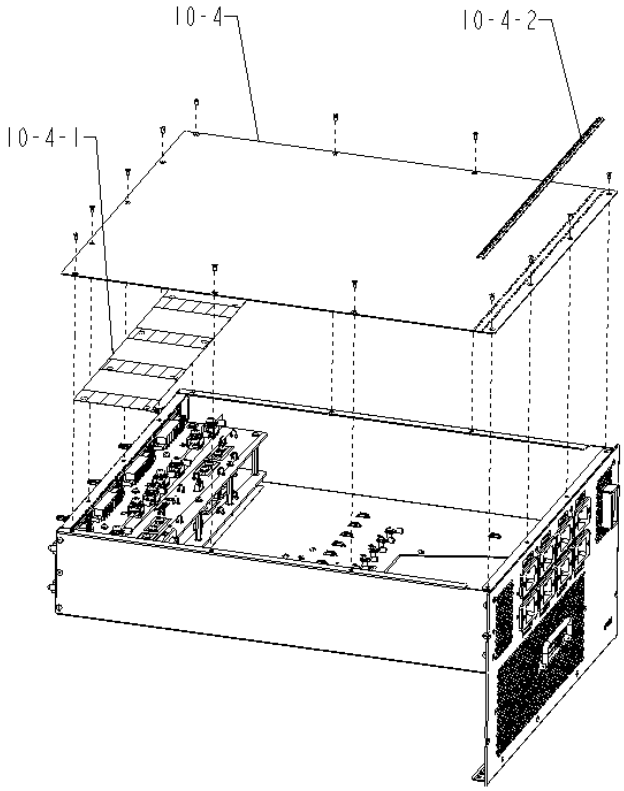

Figure 21 Treatments to the part 10

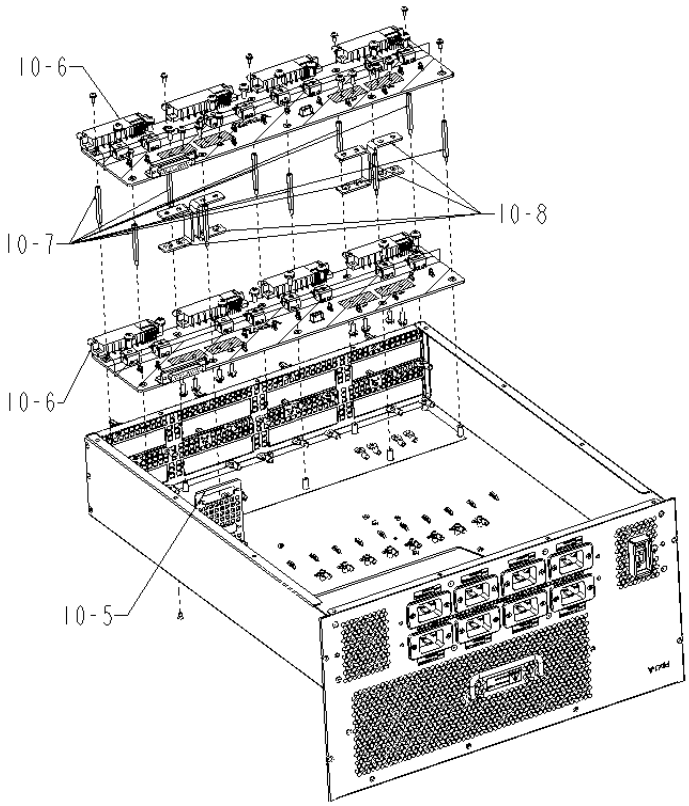

Figure 22 Treatments to the part 10

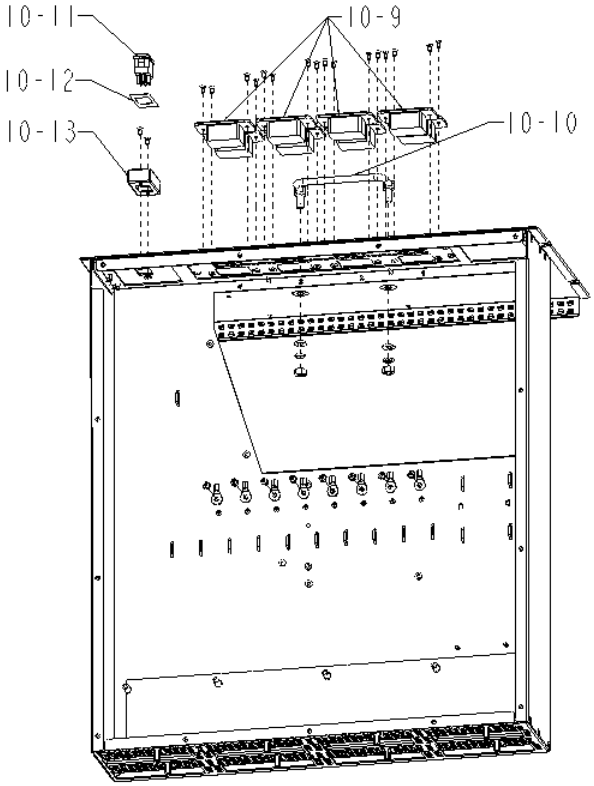

Figure 23 Treatments to the part 10

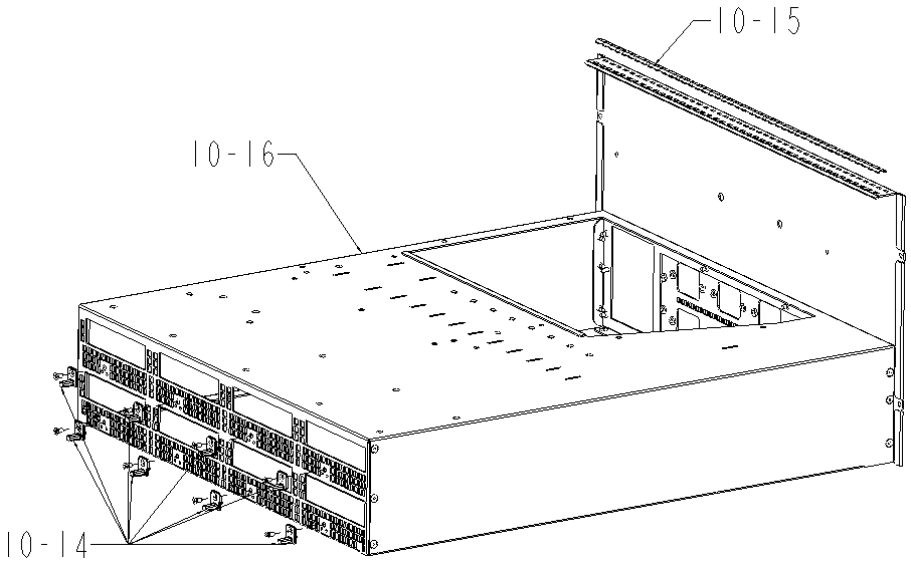

Figure 24 Treatments to the part 10

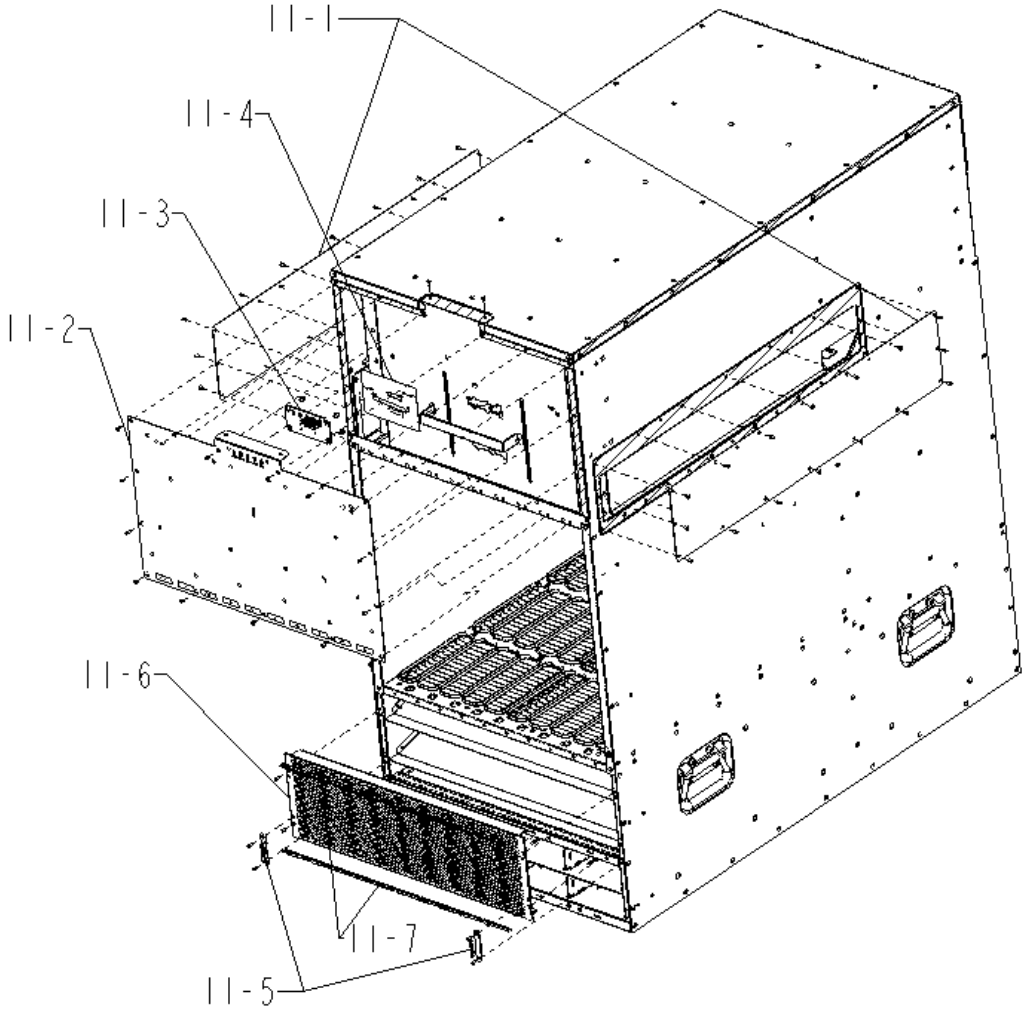

Figure 25 Treatments to the part 11

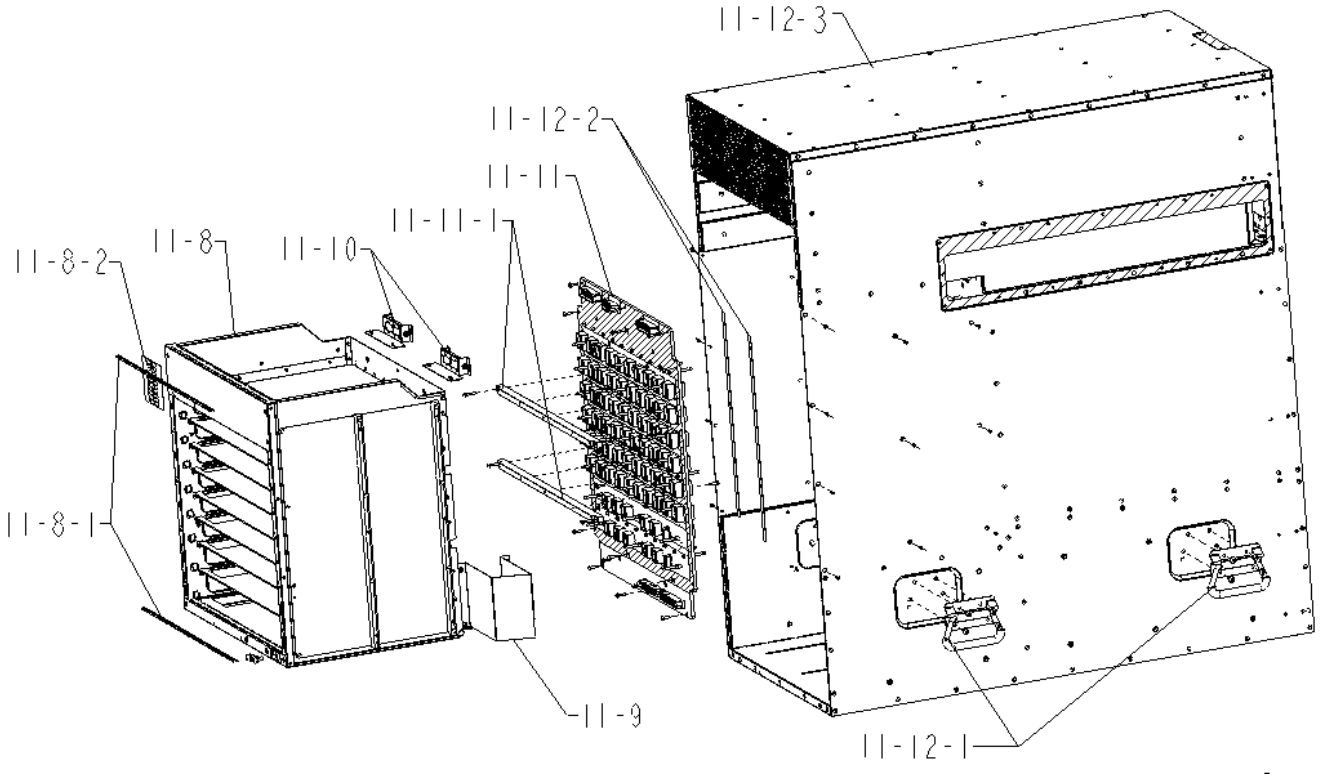

Figure 26 Treatments to the part 11

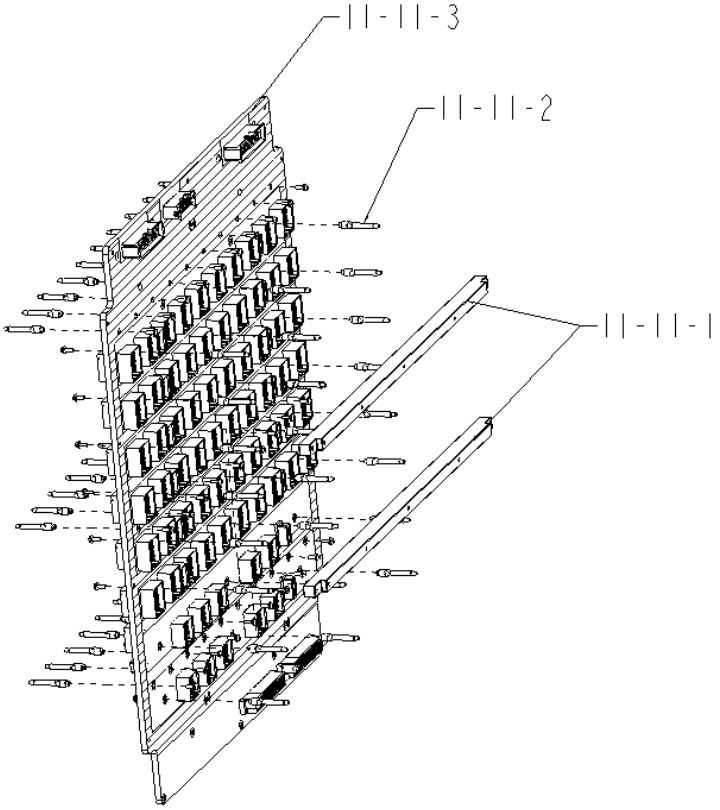

Figure 27 Treatments to the part 11-11

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	193	0.2%		Fe recycling
2		Fe	5152	4.6%		Fe recycling
3						
	3-1-3	Fe	212	0.2%		Fe recycling
	3-3	Pla,Fe	819	0.7%		
4						
	4-3	Fe	736	0.7%		Fe recycling
	4-5	Fe	301	0.3%		Fe recycling
	4-6	Al	680	0.6%		Al recycling
	4-7	Al	148	0.1%		Al recycling
	4-8	Al	400	0.4%		Al recycling
	4-9	Al	680	0.6%		Al recycling
	4-10	Al	324	0.3%		Al recycling
	4-11	Fe	2574	2.3%		Fe recycling
5						
	5-3	Fe	2180	1.9%		Fe recycling
6		Fe	2230	2.0%		Fe recycling
7						
	7-3	Fe	1205	1.1%		Fe recycling
8						
	8-3	Fe	1211	1.1%		Fe recycling
9						
	9-1	Fe	1500	1.3%		Fe recycling
	9-2	Fe	330	0.3%		Fe recycling
	9-3	Pla,Al,Cu	5500	4.9%		
	9-4	Cmplex PWB	360	0.3%	The surface of PCB is greater than 10 square centimeters;	
	9-6	Cmplex PWB	60	0.05%	The surface of PCB is greater than 10 square centimeters;	
	9-8	Al	68	0.06%		Al recycling
	9-12	Fe	3529	3.1%		Fe recycling
10						
	10-1	Fe	1503	1.3%		Fe recycling
	10-2	Cmplex PWB	330	0.3%	The surface of PCB is greater than 10 square centimeters;	
	10-3	Fe	479	0.4%		Fe recycling
	10-4	Fe	1539	1.4%		Fe

						recycling
	10-5	Fe	29	0.03%		Fe recycling
	10-6	Cmplex PWB	470	0.4%	The surface of PCB is greater than 10 square centimeters;	
	10-7	Fe	70	0.06%		Fe recycling
	10-8	Fe,Cu	120	0.1%		Fe ,Cu recycling
	10-9	Pla,Cu	35	0.03%		Pla ,Cu recycling
	10-10	Fe	37	0.03%		Fe recycling
	10-14	Al	93	0.09%		Al recycling
	10-16	Fe	3599	3.2%		Fe recycling
11						
	11-1	Fe	1052	0.9%		Fe recycling
	11-2	Fe	960	0.9%		Fe recycling
	11-3	Cmplex PWB	31	0.03%	The surface of PCB is greater than 10 square centimeters;	
	11-6	Fe	350	0.3%		Fe recycling
	11-8	Fe,Al	9200	8.2%		Fe ,Al recycling
	11-9	Fe	236	0.2%		Fe recycling
	11-10	Fe	100	0.09%		Fe recycling
	11-11-1	Al	334	0.3%		Al Frecycling
	11-11-2	Fe	213	0.2%		Fe recycling
	11-11-3	Cmplex PWB	3320	3.9%	The surface of PCB is greater than 10 square centimeters;	
	11-12-1	Pla, Fe	600	0.5%		Pla, Fe recycling
	11-12-3	Fe	52640	46.8%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2013.06.27	V0	Wang Zitao	Initial version